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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor device comprising:
  - a printed wiring board having a top surface, and a backside surface, on the side of the printed wiring board, opposite from the top surface;
  - a second semiconductor chip mounted over the top surface of the ~~module~~  
printed wiring board, including first circuits operated by at a first frequency and second circuits operated by at a second frequency;
  - a first semiconductor chip disposed so as to overlie ~~over~~ the second semiconductor chip, including the a first circuit and the a second circuit; and
  - a plurality of conductive wires electrically bonding the first semiconductor chip to the printed wiring board;

wherein the first circuit of the first semiconductor chip is disposed opposite to the second circuits of the second semiconductor chip, while the second circuit of the first semiconductor chip is disposed opposite to the first circuits of the second semiconductor chip.
2. (currently amended) A semiconductor device according to claim 1,  
wherein the first semiconductor chip and the second semiconductor chip each include a third circuit operated with at a third frequency, and  
wherein a fourth circuit operated with at a fourth frequency, wherein, and the third circuit of the first semiconductor chip is disposed opposite to the fourth

circuit of the second semiconductor chip, while the fourth circuit of the first semiconductor chip is disposed opposite to the third circuit of the second semiconductor chip.

3. (previously presented) A semiconductor device according to claim 1, further comprising:

amplifier circuits for amplifying input signals in three stages, wherein the amplifier circuits in the initial stage of the three stages are installed in the first semiconductor chip, and the amplifier circuits in second and third stages, respectively, are installed in the second semiconductor chip.

4. (currently amended) A semiconductor device according to claim 1, wherein the first and second frequencies are in the ranges of 880 MHz  $\leq$  the first frequency  $\leq$  915 MHz, and 1710 MHz  $\leq$  the second frequency  $\leq$  1785 MHz, respectively.

5. (previously presented) A semiconductor device according to claim 1, wherein the second semiconductor chip is electrically bonded to the printed wiring board with conductive wires.

6. (previously presented) A semiconductor device according to claim 1, wherein the second semiconductor chip is bonded to the printed wiring board by flip bonding.

7. (currently amended) A semiconductor device according to claim 6, wherein a first wire that is electrically bonded to the first circuit of the first semiconductor chip is disposed opposite to a first wiring of the printed wiring board, which is electrically bonded to the second circuits of the second semiconductor chip, respectively,

while a second wire that is electrically bonded to the second circuit of the first semiconductor chip is disposed opposite to a second wiring of the printed wiring board, which is electrically bonded to the first circuits of the second semiconductor chip, respectively.

8. (currently amended) A semiconductor device comprising:

a printed wiring board having a top surface, and a backside surface, on the side of the printed wiring board, opposite from the top surface;

a second semiconductor chip mounted over the top surface of the module printed wiring board, including first circuits operated by at a first frequency, and second circuits operated by at a second frequency; a plurality of first electrodes bonded to the first circuits, respectively, and a plurality of second electrodes bonded to the second circuits, respectively;

a first semiconductor chip disposed so as to overlie over the second semiconductor chip, including the a first circuit, the a second circuit, a plurality of first electrodes bonded to the first circuit, and a plurality of second electrodes bonded to the second circuit; and

a plurality of wires electrically bonding the first semiconductor chip and the second semiconductor chip to the printed wiring board, respectively;

wherein the plurality of wires bonded to the plurality of first electrodes and second electrodes of the first semiconductor chip, respectively, are disposed so as to cross a pair of sides edges, that are opposed to each other, of a top surface of the first semiconductor chip, extending in a direction intersecting a direction in which the first pads of the second semiconductor chip are arranged, and

wherein the plurality of wires bonded to the plurality of first electrodes and second electrodes of the second semiconductor chip, respectively, are disposed so as to cross a pair of sides edges, that are opposed to each other, of a top surface of the second semiconductor chip, extending in a direction intersecting a direction in which the first electrodes of the first semiconductor chip are arranged.

9. (currently amended) A semiconductor device according to claim 8, wherein a the wiring direction of the plurality of wires bonded to the plurality of first electrodes and second electrodes of the first semiconductor chip, respectively, intersects a the wiring direction of the plurality of wires bonded to the plurality of first electrodes and second electrodes of the second semiconductor chip, respectively, at right angles.

10. (currently amended) A semiconductor device comprising:  
a printed wiring board having a top surface, and a backside surface, on the side of the printed wiring board, opposite from the top surface;  
a second semiconductor chip mounted over the top surface of the module printed wiring board, including first circuits operated by at a first frequency and second circuits operated by at a second frequency;

a first semiconductor chip disposed so as to overlie ~~over~~ the second semiconductor chip, including the a first circuit and the a second circuit; and a plurality of conductive wires electrically bonding the first semiconductor chip to the printed wiring board; ;

wherein a first wiring layer for GND is provided between the first circuit and the second circuit of the first semiconductor chip, and a second wiring layer for GND is provided between the first circuits and the second circuits of the second semiconductor chip.

11. (previously presented) A semiconductor device according to claim 10, wherein the first circuit of the first semiconductor chip is disposed opposite to the second circuits of the second semiconductor chip, and the second circuit of the first semiconductor chip is disposed opposite to the first circuits of the second semiconductor chip.

12. (currently amended) A semiconductor device comprising:  
a printed wiring board having a top surface, and a backside surface, on the side of the printed wiring board, opposite from the top surface;  
a second semiconductor chip mounted over the top surface of the module printed wiring board, including first circuits operated by at a first frequency and second circuits operated by at a second frequency;  
a first semiconductor chip disposed so as to overlie ~~over~~ the second semiconductor chip, including the a first circuit and the a second circuit; and a plurality of conductive wires electrically bonding the first semiconductor chip to the printed wiring board; ;

wherein the wire bonded to the first circuit of the first semiconductor chip and the wires bonded to the second circuits of the second semiconductor chip, respectively, are disposed in such a way as to face each other, and the wire bonded to the second circuit of the first semiconductor chip, and the wires bonded to the first circuits of the second semiconductor chip, respectively, are disposed in such a way as to face each other.

13. (previously presented) A semiconductor device according to claim 12, wherein the first circuit of the first semiconductor chip is disposed opposite to the second circuits of the second semiconductor chip, respectively, and the second circuit of the first semiconductor chip is disposed opposite to the first circuits of the second semiconductor chip, respectively.